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(12) **United States Design Patent**
Phillips et al.

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(54) **SENSOR MODULE**

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(73) Assignee: **Samsung Electronics Co., Ltd.**, Suwon-si, Gyeonggi-do (KR)

(**) Term: **14 Years**

(21) Appl. No.: **29/491,668**

(22) Filed: **May 22, 2014**

(51) **LOC (10) Cl.** **10-04**

(52) **U.S. Cl.**
USPC **D10/103**; D11/3

(58) **Field of Classification Search**
CPC G08G 1/096883; G08G 1/096872; G08G 1/096775; G01C 21/16; G01C 21/3688; G01C 21/30; G01V 8/20; G01J 5/02; G01J 5/023; G01J 5/24; G01J 5/10; G01J 5/20; G01J 5/0235; G01J 5/08; G01J 5/0853; G01J 5/33; G01J 5/34
USPC .... D10/30-39, 65, 70, 78, 97, 98, 103; D11/3; D13/173-177; D14/138 R, D14/203.5, 247, 338-340, 344, 346, 347; D24/167, 168
See application file for complete search history.

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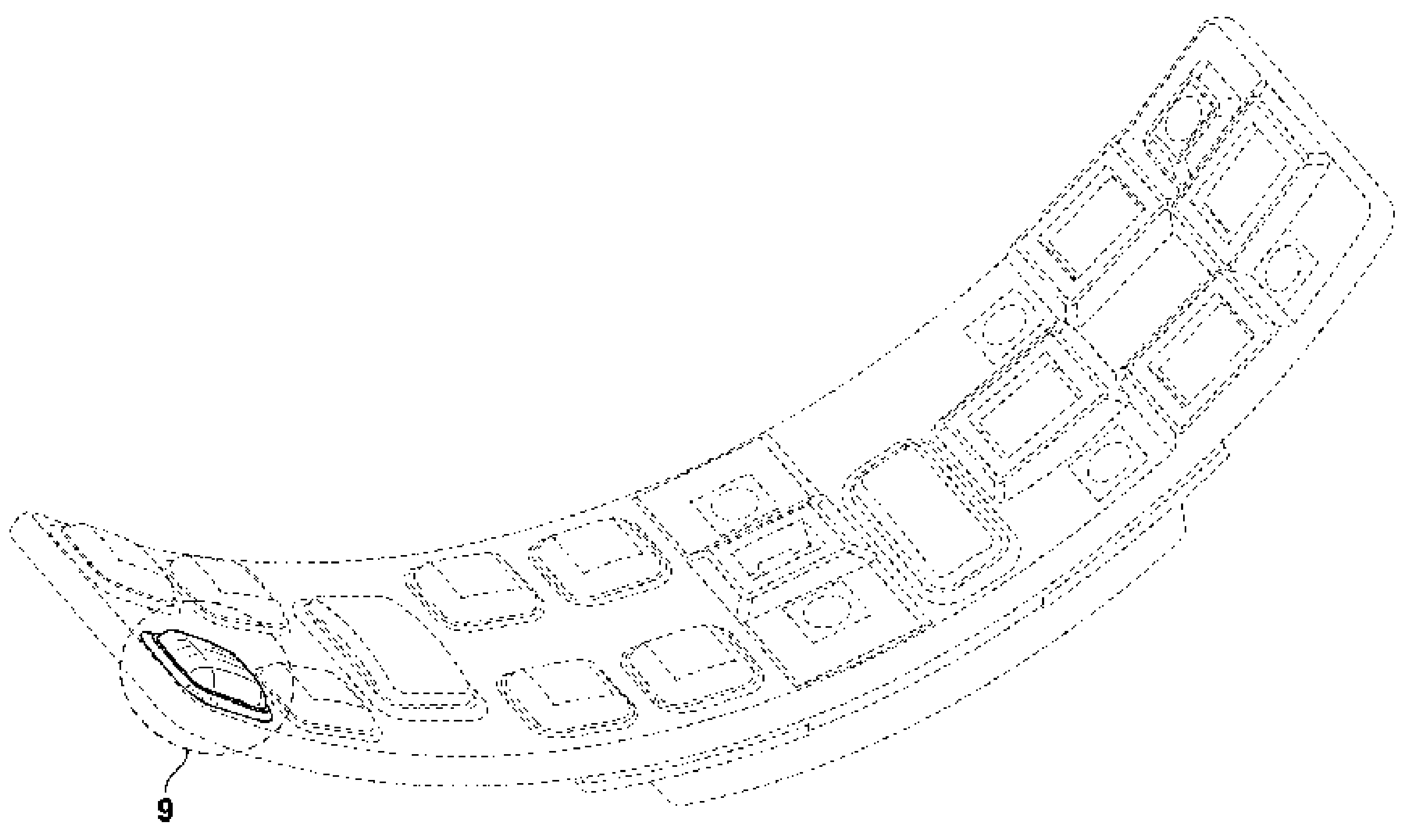
(57) **CLAIM**

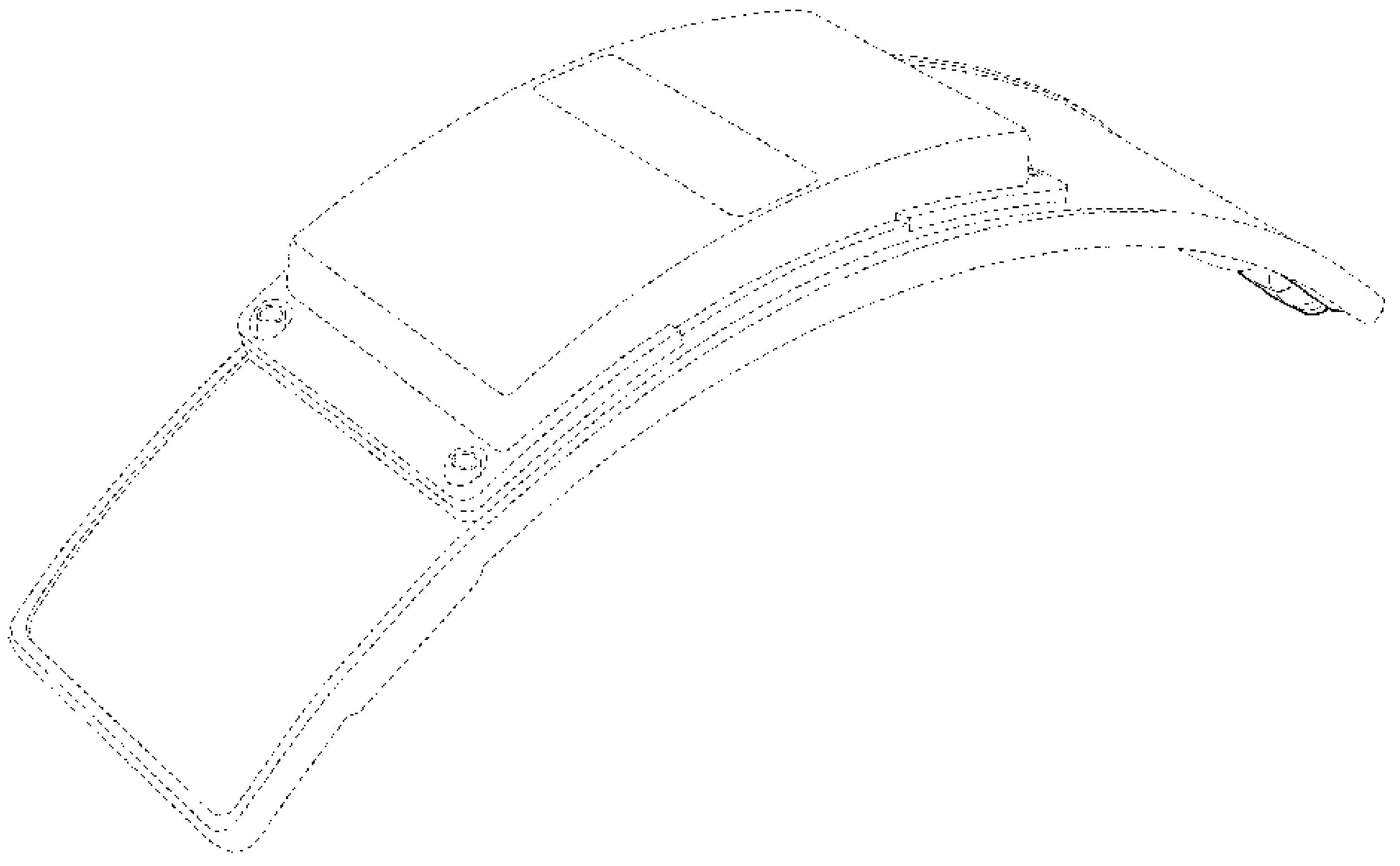
The ornamental design for a sensor module, as shown and described.

DESCRIPTION

This application makes reference to:
U.S. Design application Ser. No. 29/491,674 filed May 22, 2014.
The above referenced application, and all of the subject matter disclosed therein, is incorporated herein by reference in its entirety.
FIG. **1** is a top left front perspective view of a sensor module showing our new design;
FIG. **2** is a rear elevation view thereof;
FIG. **3** is a front elevation view thereof;
FIG. **4** is a right side elevation view thereof;
FIG. **5** is a left side elevation view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof;
FIG. **8** is a bottom right rear perspective view thereof; and,
FIG. **9** is an enlarged view of the portion encircled in FIG. **1**.
The dashed broken lines are for environmental purposes only and form no part of the claimed design.
The dashed broken lines in FIG. **1** labeled with the number "9" encircle a portion of the claimed design that is illustrated in an enlargement in FIG. **9**.
Any views of the sensor module that are not shown in the figures form no part of the claimed design.

1 Claim, 5 Drawing Sheets





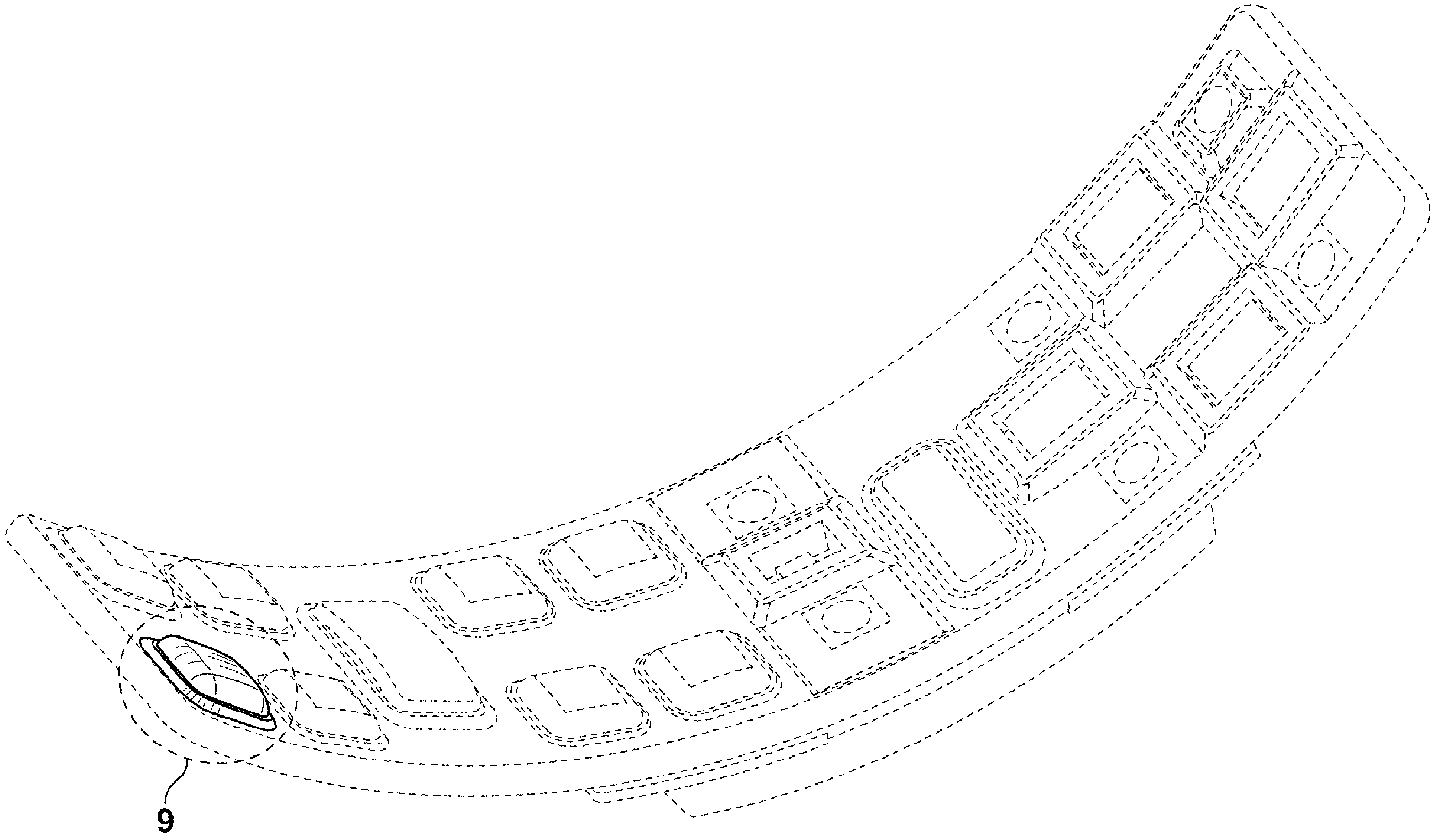


FIG. 1

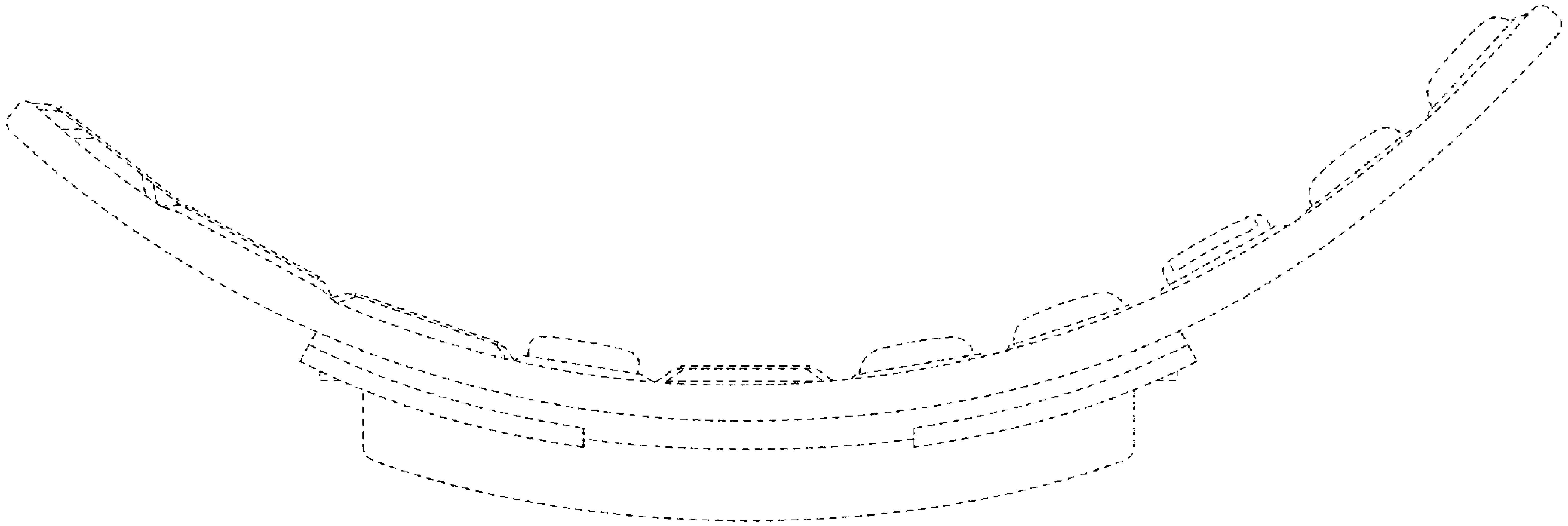


FIG. 2

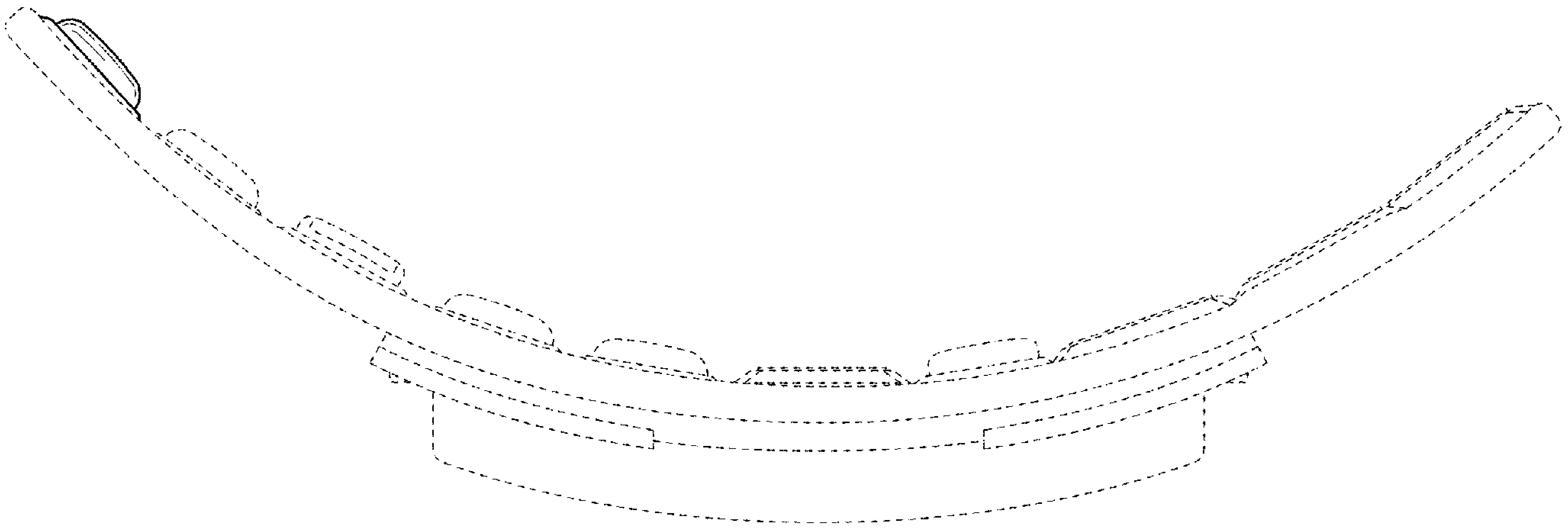


FIG. 3

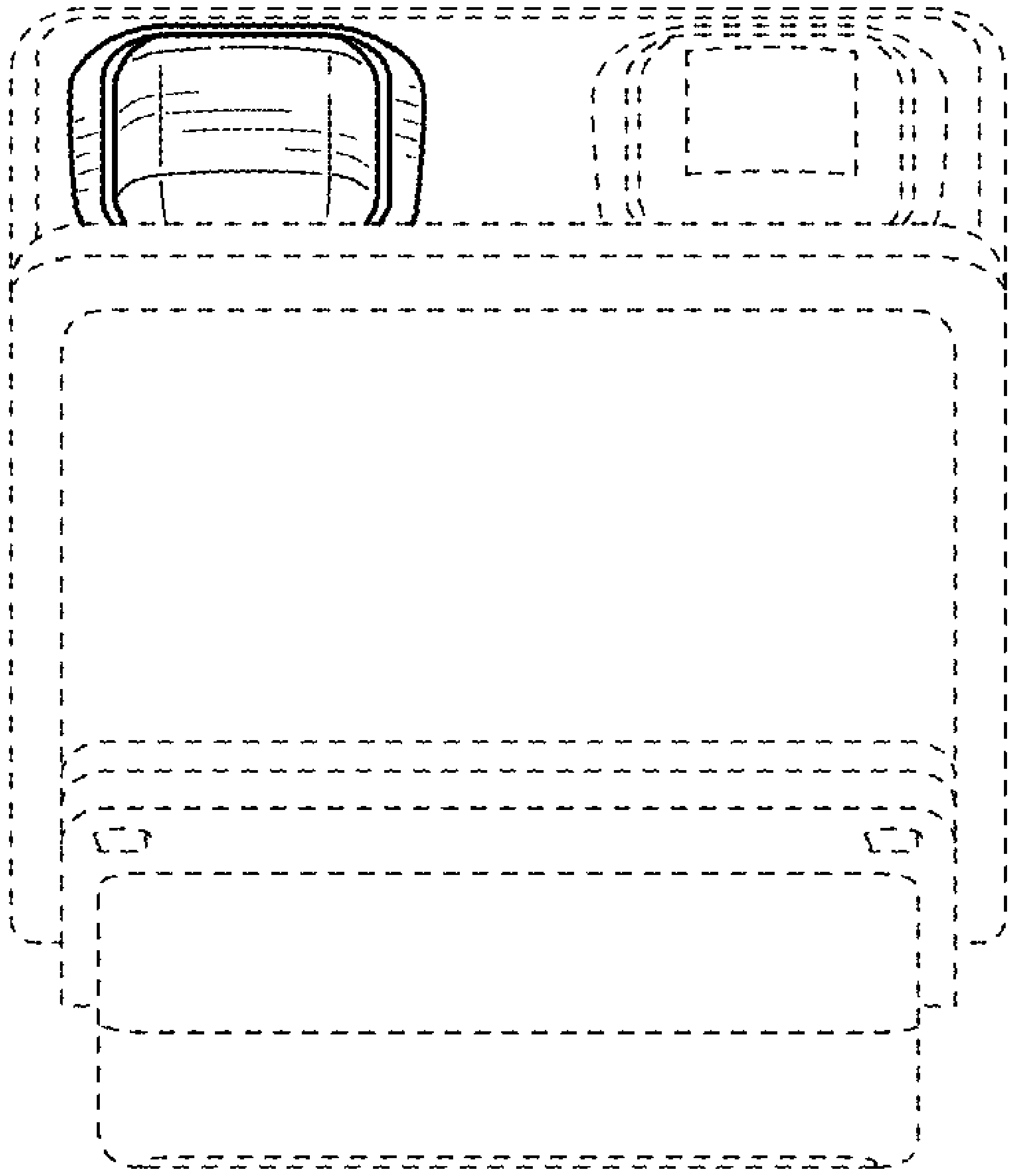


FIG. 4

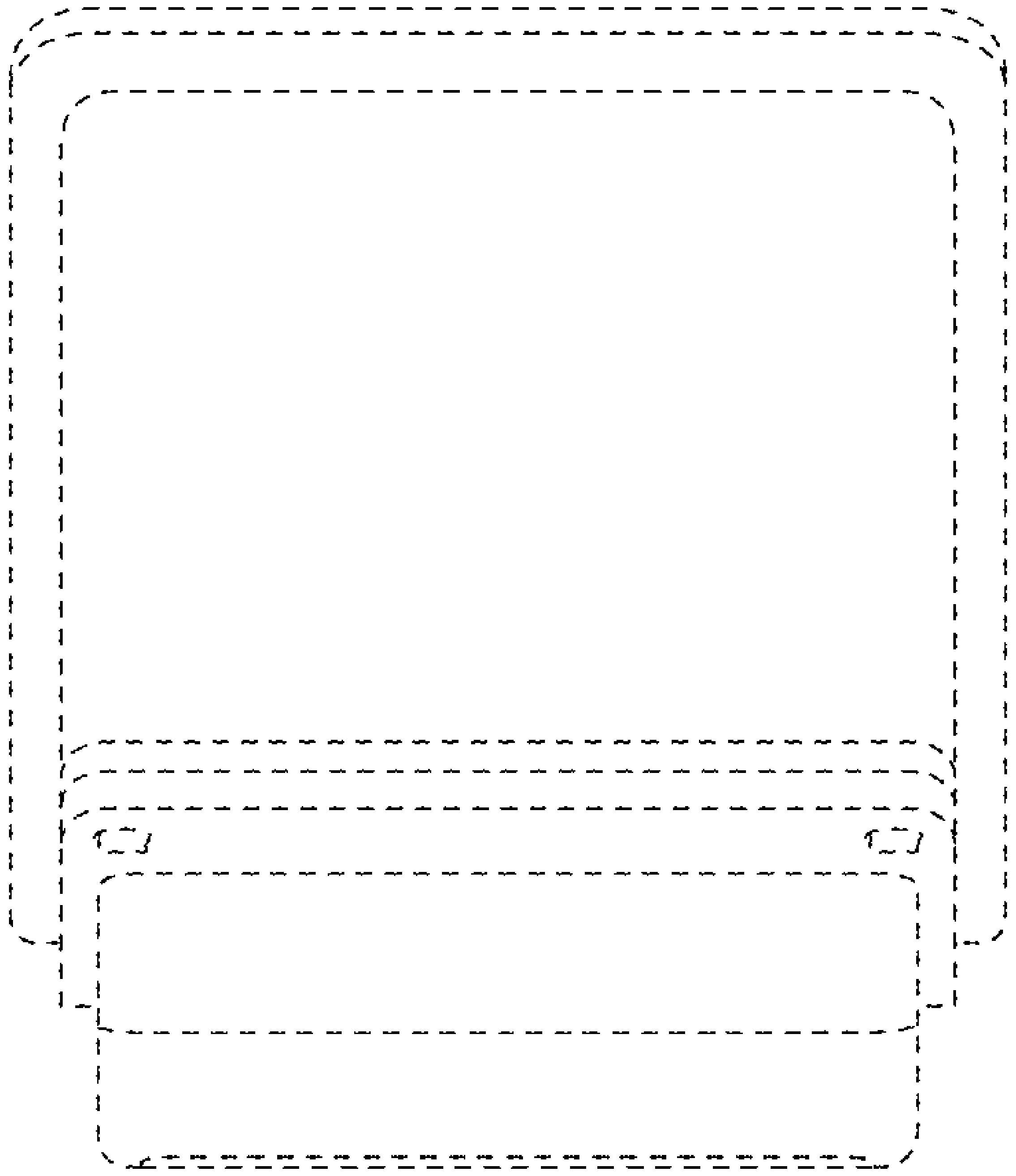


FIG. 5

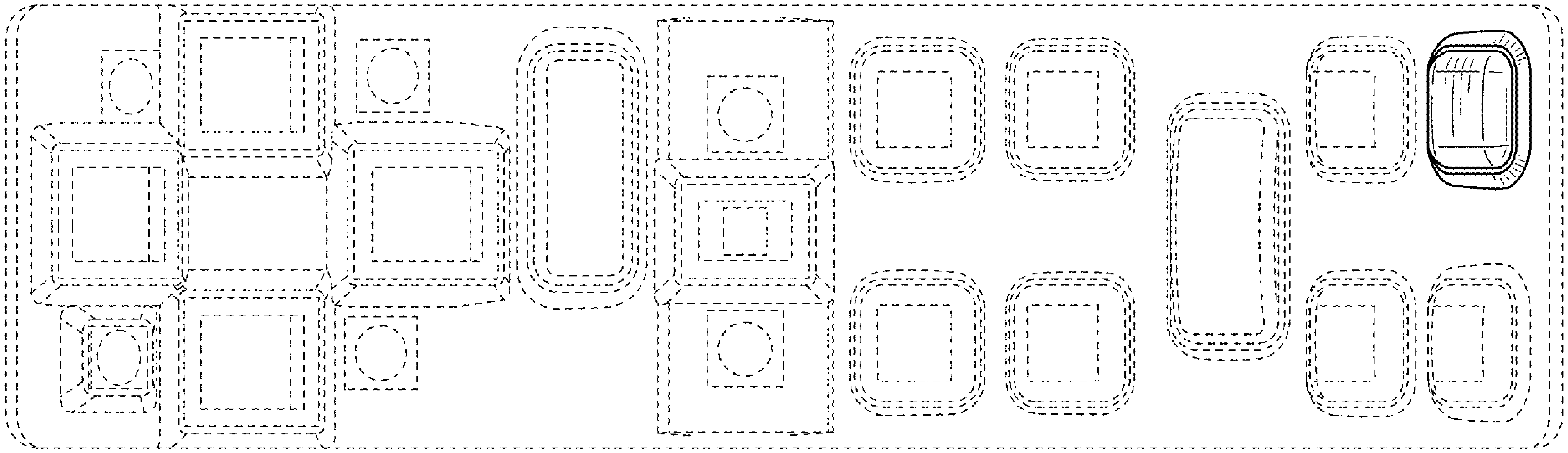


FIG. 6

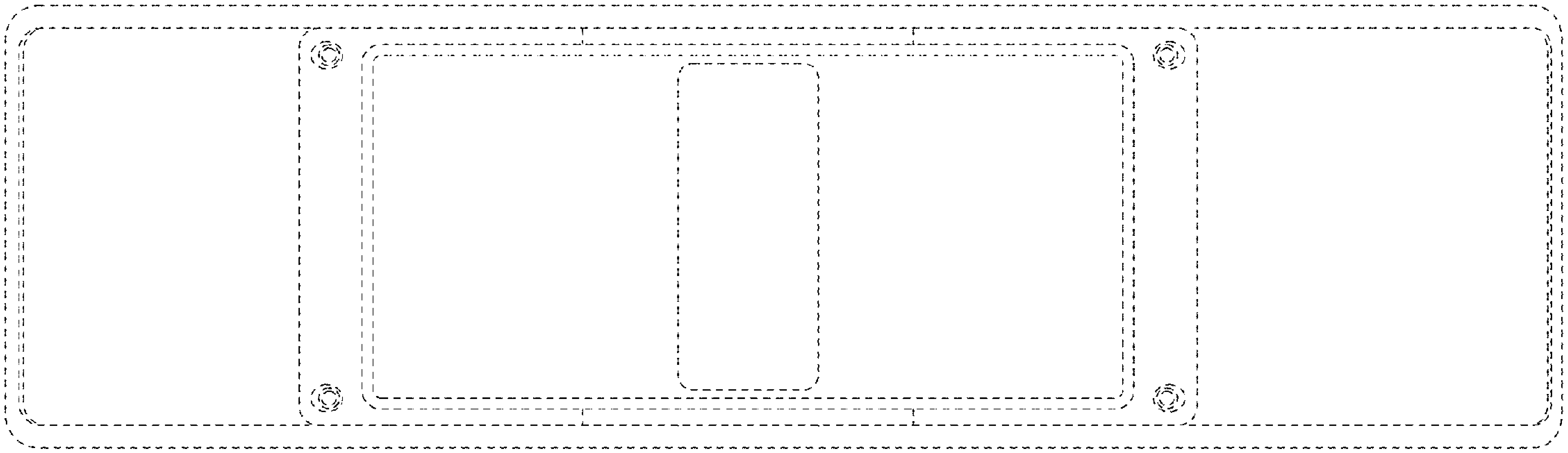


FIG. 7

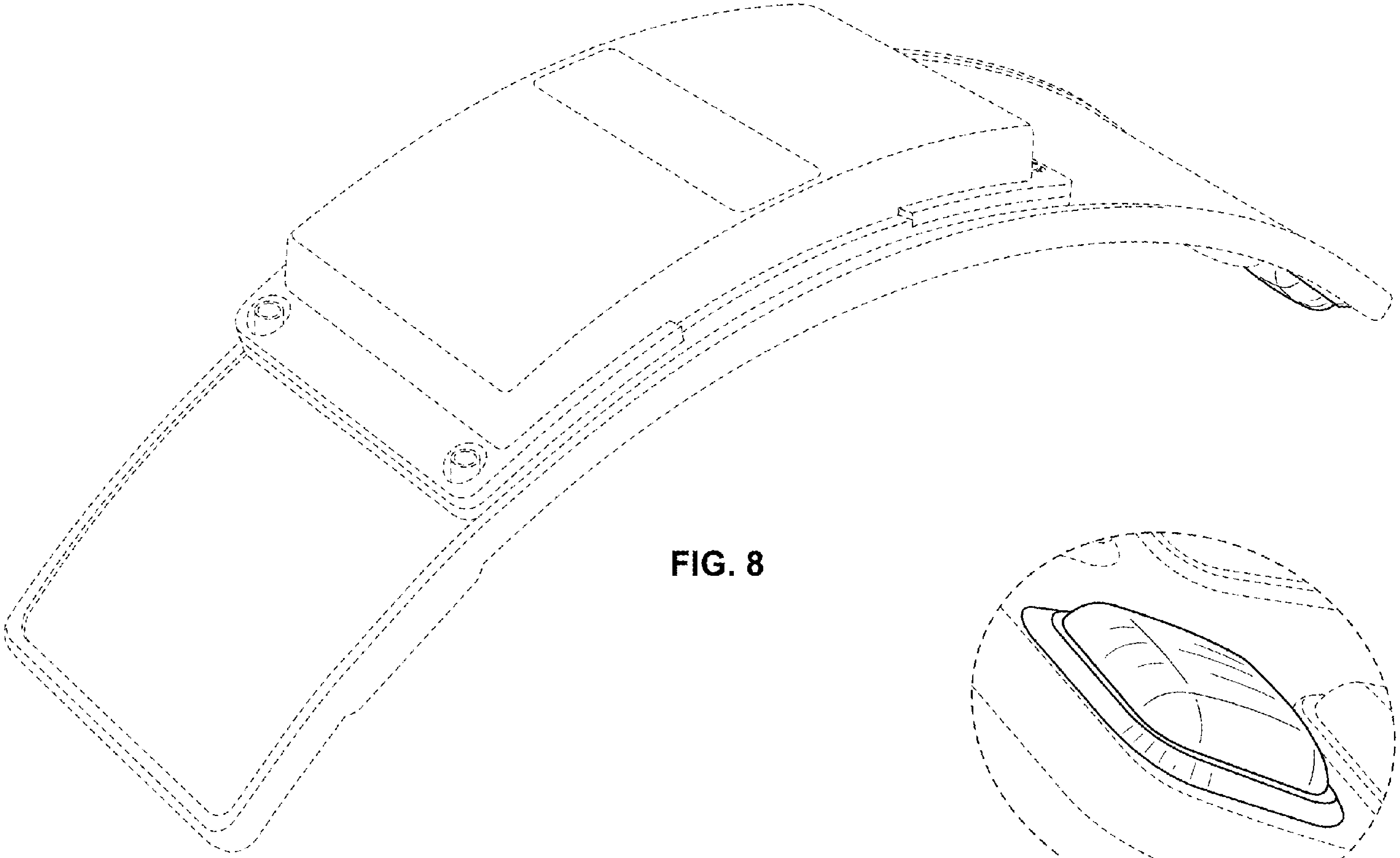


FIG. 8

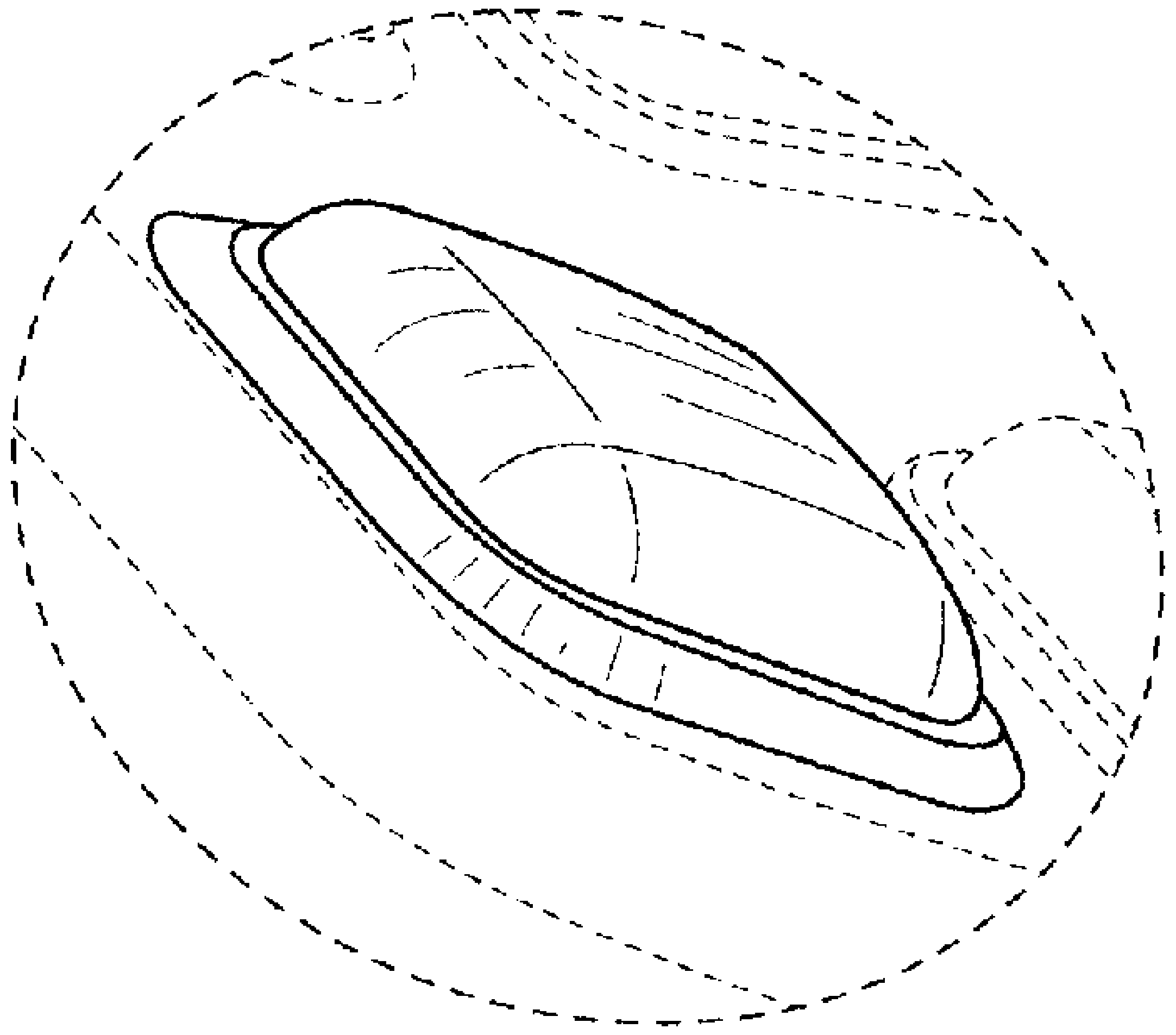


FIG. 9